Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

- 1-10. (Canceled).
- 11. (Withdrawn) A method of fabricating ceramics,

wherein a film having a predetermined thickness is formed by repeating several times a step of forming a ceramic film having a predetermined thickness by feeding an electromagnetic wave and active species of a substance which is at least part of raw materials for the ceramics to a predetermined region.

- 12. (Withdrawn) The method of fabricating ceramics as defined in claim 11, wherein a film including a substance which is part of the raw materials for the ceramics is formed in the predetermined region.
- 13. (Withdrawn) The method of fabricating ceramics as defined in claim 11, wherein the thickness of the ceramic film is 5 nm to 30 nm.
- 14. (Withdrawn) The method of fabricating ceramics as defined in claim 11, wherein the ceramic film is formed on part of a substrate.
 - 15. (Withdrawn) A method of fabricating ceramics, comprising:
 - a first step of forming a first ceramic film; and

a second step of feeding at least one of an electromagnetic wave and active species to the first ceramic film to form a second ceramic film which has a crystal structure differing from the crystal structure of the first ceramic film,

wherein a film having a predetermined thickness is formed by performing alternately the first and second steps.

16. (Withdrawn) The method of fabricating ceramics as defined in claim 15, wherein the thickness of the first ceramic film is 5 nm to 30 nm.

- 17. (Withdrawn) The method of fabricating ceramics as defined in claim 15, wherein the first ceramic film is formed on part of a substrate.
- 18. (Withdrawn) The method of fabricating ceramics as defined in claim 15, wherein the first ceramic film is formed of ceramics in an amorphous state.
- 19. (Withdrawn) The method of fabricating ceramics as defined in claim 15, wherein the first ceramic film is formed of ceramics having low crystallinity.
- 20. (Withdrawn) The method of fabricating ceramics as defined in claim 11, wherein the active species of a substance which is at least part of the raw materials for the ceramics is a radical, an ion, or ozone obtained by activating a substance containing oxygen or nitrogen.
- 21. (Withdrawn) The method of fabricating ceramics as defined in claim 15, wherein the active species is a radical, an ion, or ozone obtained by activating a substance containing oxygen or nitrogen.
- 22. (Withdrawn) The method of fabricating ceramics as defined in claim 11, wherein in addition to the active species, ions obtained by activating inert gas is also fed to the predetermined region.
- 23. (Currently Amended) A method of fabricating ceramics,
 wherein a region for forming a ceramic film is part of a substrate; and
 the method comprising a step of forming the ceramic film by feeding an
 electromagnetic wave and active species of a substance which is at least part of raw materials
 for the ceramics to a predetermined region—; and

further comprising a step of:

forming a film-forming region having affinity to ceramics to be formed and a non-film-forming region having no affinity to ceramics to be formed on a surface of the substrate, to form self-alignably a ceramic film in the film-forming region.

- 24. (Original) The method of fabricating ceramics as defined in claim 23, wherein a film including a substance which is part of the raw materials for the ceramics is formed in the predetermined region.
- 25. (Currently Amended) A method of fabricating ceramics,
 wherein a region for forming a ceramic film is part of a substrate; and
 the method comprising a step of feeding at least one of active species and an
 electromagnetic wave to a first ceramic film to form a second ceramic film which has a crystal
 structure differing from the crystal structure of the first ceramic film; and

further comprising a step of:

forming a film-forming region having affinity to ceramics to be formed and a non-film-forming region having no affinity to ceramics to be formed on a surface of the substrate, to form self-alignably a ceramic film in the film-forming region.

- 26. (Canceled).
- 27. (Original) The method of fabricating ceramics as defined in claim 25, wherein the first ceramic film is formed of ceramics in an amorphous state.
- 28. (Original) The method of fabricating ceramics as defined in claim 25, wherein the first ceramic film is formed of ceramics having low crystallinity.
- 29. (Original) The method of fabricating ceramics as defined in claim 23, wherein the active species of a substance which is at least part of the raw materials for the ceramics is a radical, an ion, or ozone obtained by activating a substance containing oxygen or nitrogen.
- 30. (Original) The method of fabricating ceramics as defined in claim 25, wherein the active species is a radical or an ion obtained by activating a substance containing oxygen or nitrogen.

- 31. (Original) The method of fabricating ceramics as defined in claim 23, wherein in addition to the active species, ions obtained by activating inert gas are fed to the predetermined region.
- 32. (Original) The method of fabricating ceramics as defined in claim 23, wherein the thickness of the ceramic film is 5 nm to 30 nm.
- 33. (Original) The method of fabricating ceramics as defined in claim 25, wherein the thickness of the second ceramic film is 5 nm to 30 nm.
- 34. (Original) The method of fabricating ceramics as defined in claim 23, wherein the step of forming the ceramics is repeated several times.
- 35. (Previously Presented) The method of fabricating ceramics as defined in claim 23,

wherein at least one of the active species and the electromagnetic wave is fed to part of a substrate.

- 36. (Original) The method of fabricating ceramics as defined in claim 35, wherein the substrate is relatively moved when at least one of the active species and the electromagnetic wave is fed to the part of the substrate.
- 37. (Previously Presented) The method of fabricating ceramics as defined in claim25,

wherein the first ceramic film is formed by a coating method, the liquid source misted chemical deposition (LSMCD), the chemical deposition (CVD), or a sputtering method.

- 38. (Original) The method of fabricating ceramics as defined in claim 37, wherein the first ceramic film is formed by LSMCD or CVD.
- 39. (Previously Presented) The method of fabricating ceramics as defined in claim23,

wherein the ceramic film or the second ceramic film is formed of ferroelectrics.

40. (Previously Presented) The method of fabricating ceramics as defined in claim 23,

wherein the ceramic film or the second ceramic film is formed at a temperature of less than 600°C.

- 41-51. (Canceled).
- 52. (Withdrawn) A method of fabricating ceramics, comprising:

forming a film forming region having affinity to ceramics to be formed and a non-film forming region having no affinity to ceramics to be formed on a surface of a substrate;

forming a ceramic film in the film-forming region in a self aligning way by feeding fine particles of a substance which is at least part of raw materials for a ceramic film by liquid source misted chemical deposition (LSMCD) to the film-forming region having affinity to ceramics and the non-film-forming regions having no affinity to ceramics; and

crystallizing the ceramic film by feeding an electromagnetic wave to the ceramic film.

53. (Withdrawn) The method of fabricating ceramics as defined in claim 52, further comprising

feeding an active species of a substance which is part of raw materials for the ceramic film to the ceramic film in the step of forming the ceramic film or the step of crystallizing the ceramic film.

54. (Withdrawn) A method of forming ceramics, comprising:

forming a film-forming region having affinity to ceramics to be formed and a non-film-forming regions having no affinity to ceramics to be formed on a surface of a substrate;

forming a ceramic film in the film-forming region in a self-aligning way by feeding fine particles of a substance which is at least part of raw material for a ceramic film by liquid source misted chemical deposition (LSMCD) to the film-forming region having affinity to ceramics and the non-film-forming regions having no affinity to ceramics; and

crystallizing the ceramic film by feeding an active species of a substance which is part of raw materials for the ceramic film to the ceramic film.

- 55. (Withdrawn) The method according to claim 54, further comprising crystallizing the ceramic film by feeding an electromagnetic wave to the ceramic film, in the step of forming the ceramic film or the step of crystallizing the ceramic film.
 - 56. (Canceled).
- 57. (Currently Amended) A method of fabricating ceramics,
 wherein a region for forming a ceramic film is part of a substrate; and
 the method comprising a step for forming the ceramic film by feeding active
 species of a substance which is at least part of raw materials for the ceramics to a
 predetermined region—; and

further comprising a step of:

forming a film-forming region having affinity to ceramics to be formed and a non-film-forming region having no affinity to ceramics to be formed on a surface of the substrate, to form self-alignably a ceramic film in the film-forming region.

- 58. (Canceled).
- 59. (Currently Amended) A method of fabricating ceramics, wherein a region for forming a ceramic film is part of a substrate; and

the method comprising forming the ceramic film by feeding active species of a substance which is at least part of raw materials for the ceramics to a predetermined region that is smaller than an entire surface of the substrate.: and

further comprising a step of:

forming a film-forming region having affinity to ceramics to be formed and a non-film-forming region having no affinity to ceramics to be formed on a surface of the substrate, to form self-alignably a ceramic film in the film-forming region.

60. (Withdrawn) A ceramic fabrication device, comprising:

apparatus that forms a ceramic film having a predetermined thickness including a device that feeds active species of a substance which is at least part of raw materials for the ceramics to a predetermined region of a substrate, the predetermined region being smaller than an entire surface of the substrate.